

General Description

It combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$. It is suitable for automotive application.

Features

- AEC-Q101 Qualified
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

Application

- BLDC Motor driver
- DC-DC
- Load Switch

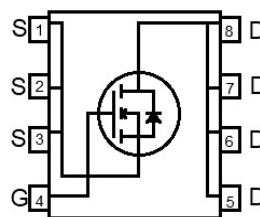
Ordering Information:

Part NO.	ZMSA250N10N
Marking	ZMS250N10
Packing Information	REEL TAPE
Basic ordering unit (pcs)	3000

Absolute Maximum Ratings ($T_C=25^{\circ}\text{C}$)

Parameter	Symbol	Conditions	Value	Unit
Drain-Source Voltage	V_{DS}		100	V
Gate-Source Voltage ^①	V_{GS}		± 20	V
Continuous Drain Current	I_D	$T_C=25^{\circ}\text{C}$	34	A
	I_D	$T_C=75^{\circ}\text{C}$	28	A
	I_D	$T_C=100^{\circ}\text{C}$	24	A
Pulsed Drain Current	I_{DM}	Pulsed; $t_p \leq 10 \mu\text{s}$; $T_{mb} = 25^{\circ}\text{C}$;	102	A
Total Power Dissipation	P_D	$T_C=25^{\circ}\text{C}$	63	W
Total Power Dissipation	P_D	$T_A=25^{\circ}\text{C}$	2.5	W
Operating Junction Temperature	T_J		-55 to +175	$^{\circ}\text{C}$
Storage Temperature	T_{STG}		-55 to +175	$^{\circ}\text{C}$
Single Pulse Avalanche Energy	E_{AS}	$L=0.1\text{mH}$, $V_{GS}=10\text{V}$, $R_g=25\Omega$,	18	mJ
		$L=0.5\text{mH}$, $V_{GS}=10\text{V}$, $R_g=25\Omega$,	38	mJ
ESD Level (HBM)	CLASS 1B			

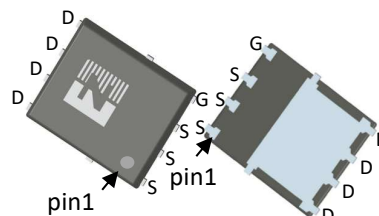
Product Summary



$$V_{DS} = 100\text{V}$$

$$R_{DS(ON)} = 22\text{m}\Omega$$

$$I_D = 34\text{A}$$



DFN5*6



•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}		-	2.4	°C/W
Thermal resistance, junction-ambient ^②	R_{thJA}		-	60	°C/W
Soldering temperature (total time<10s)	Tsold		-	260	°C

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	100			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1.3	1.8	2.5	V
Drain-Source Leakage Current	I_{DSS}	$V_{GS}=0V, V_{DS}=100V$			1.0	μA
Gate- Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$			100	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=9A$		22	25	m Ω
		$V_{GS}=4.5V, I_D=6A$		32	41	m Ω
Forward Transconductance	g_{FS}	$V_{DS}=5V, I_{SD}=10A$		6		S
Diode Forward Voltage	V_{FSD}	$V_{GS}=0V, I_{SD}=9A$			1.3	V

•Dynamic characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Input capacitance	C_{iss}	$f=1MHz, V_{DS}=25V$	-	550	-	pF
Output capacitance	C_{oss}		-	262	-	
Reverse transfer capacitance	C_{rss}		-	28	-	
Gate Resistance	R_g	$f=1MHz$	-	1.3		Ω
Total gate charge	Q_g	$V_{DD}=15V, I_D=20A, V_{GS}=10V$	-	12	-	nC
	$Q_g(4.5V)$		-	6	-	
Gate - Source charge	Q_{gs}		-	3.4	-	
Gate - Drain charge	Q_{gd}		-	1.6	-	
Turn-ON Delay time	$t_{D(on)}$	$V_{GS}=10V, V_{DS}=15V, R_G=3.3\Omega, I_D=20A$	-	8	-	ns
Turn-ON Rise time	t_r		-	6	-	ns
Turn-Off Delay time	$t_{D(off)}$		-	43	-	ns
Turn-Off Fall time	t_f		-	32	-	ns
Reverse Recovery Time	t_{RR}	$V_{DD}=20V, dI_S/dt=100A/\mu s, I_S=20A$	-	75	-	ns
Reverse Recovery Charge	Q_{RR}		-	130	-	nC



Fig.1 Gate-Charge Characteristics

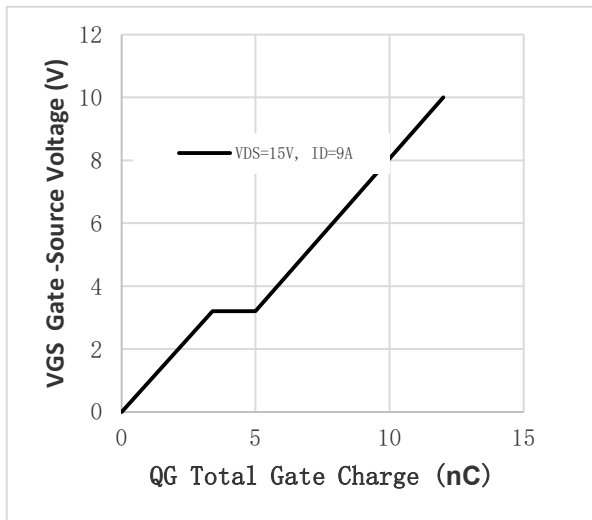


Fig.2 Capacitance Characteristics

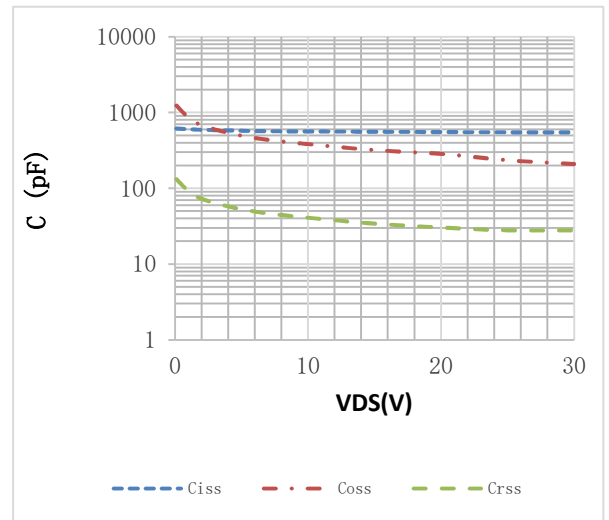


Fig.3 Power Dissipation

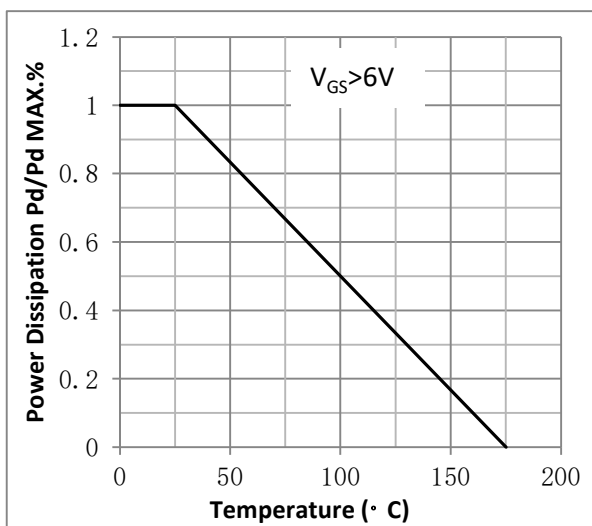


Fig.4 Typical output Characteristics

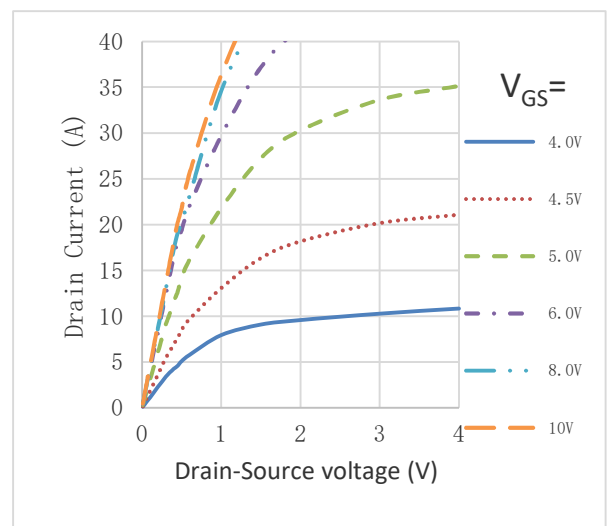


Fig.5 Threshold Voltage V.S Junction Temperature

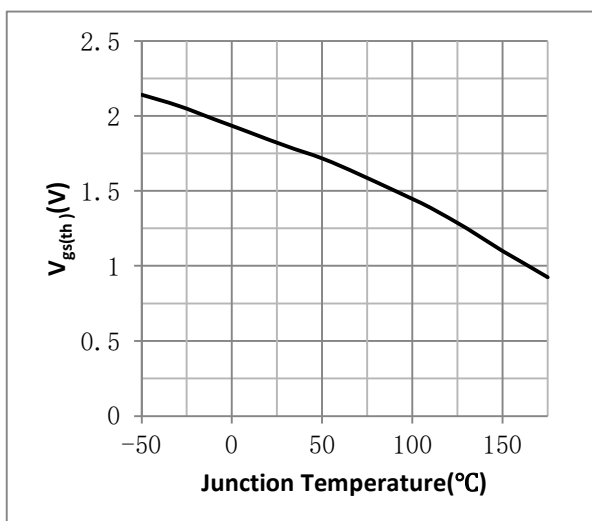


Fig.6 Resistance V.S Drain Current

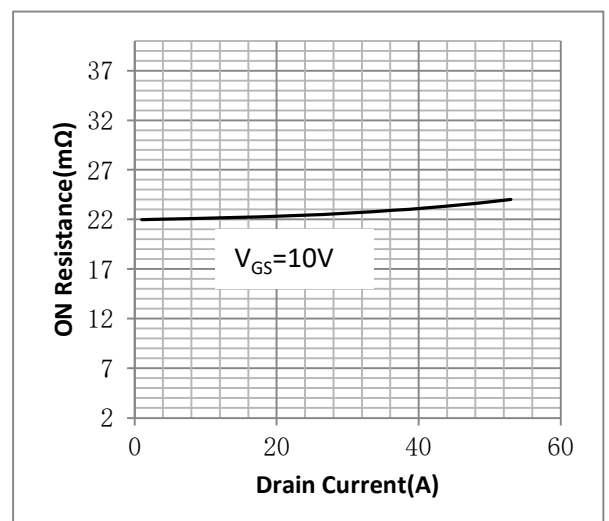


Fig.7 On-Resistance VS Gate Source Voltage

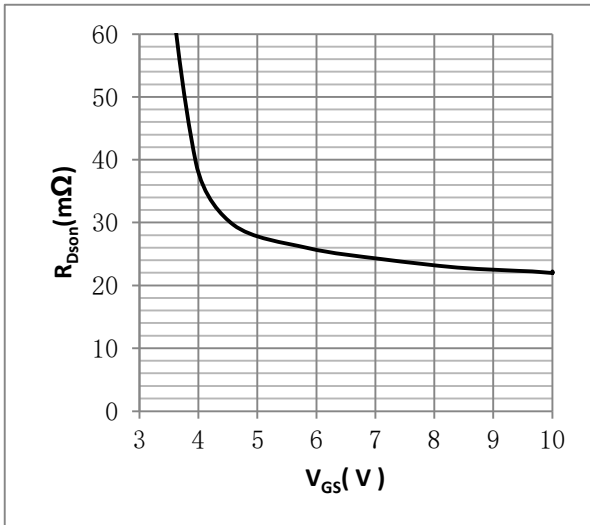


Fig.8 On-Resistance V.S Junction Temperature

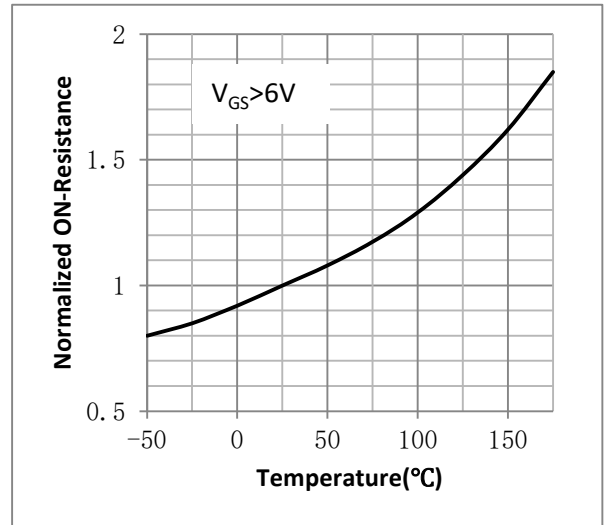


Figure 9. Diode Forward Voltage vs. Current

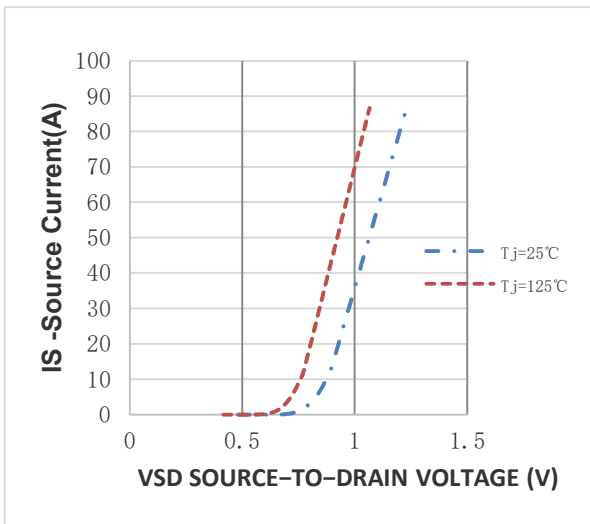


Figure 10. Transfer Characteristics

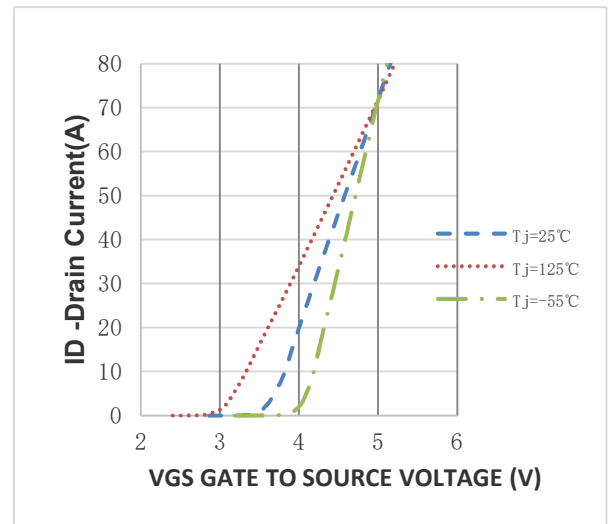


Fig.11 Safe Operating Area

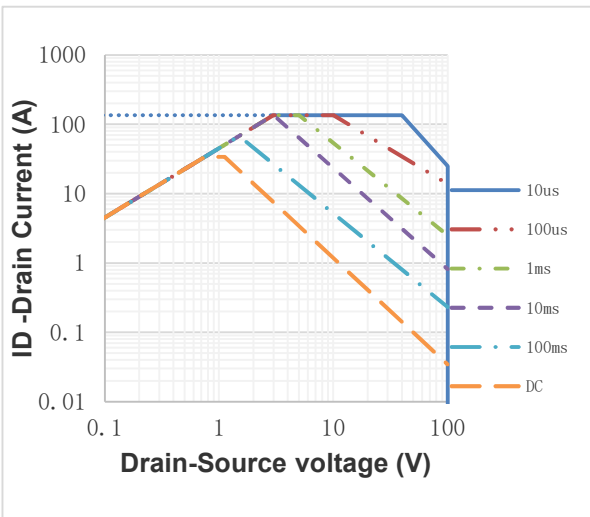
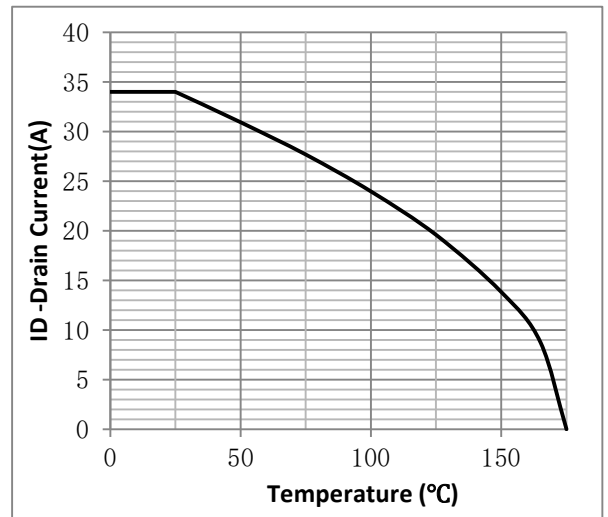
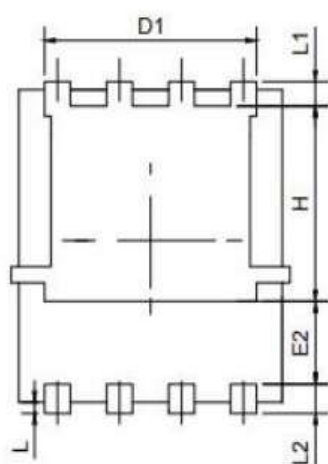
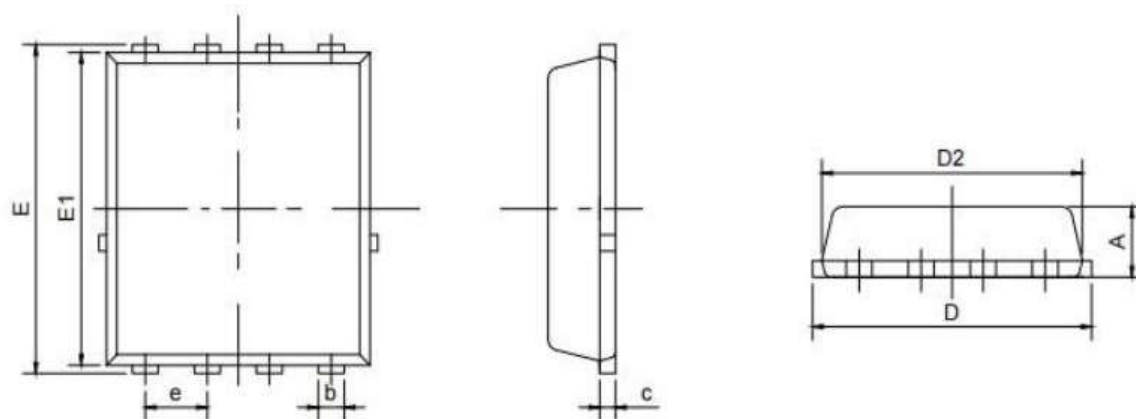


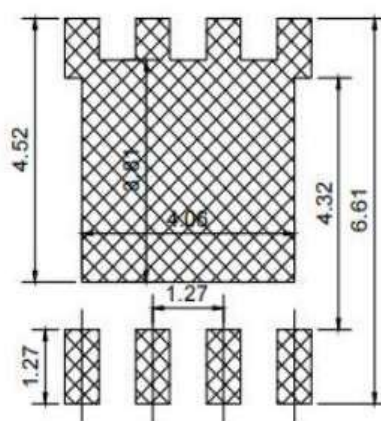
Fig.12 ID vs. Case Temperature^③



•DFN5*6 Package Outline



Land Pattern
(Only for Reference)



S Y M B O L S	COMMON	
	UNIT: mm	
	MIN.	MAX.
A	0.90	1.17
b	0.30	0.51
c	0.15	0.35
D	4.80	5.40
D1	4.00	4.40
D2	4.80	5.00
E	5.90	6.25
E1	5.65	5.85
E2	1.10	-
e	1.27BSC	
L	0.05	0.25
L1	0.28	0.65
L2	0.38	0.71
H	3.30	3.90

Note:

- ① Pulse : $V_{GS}=+20V/-20V$, Duty cycle=50%, $T_j=175^{\circ}C$, $t=1000$ hours; For DC , the following test conditions can be passed: $V_{GS}=+20V/-10V$, $T_j=175^{\circ}C$, $t=1000$ hours;
- ② Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate;
- ③ Practically the current will be limited by PCB, thermal design and operating temperature. $V_{GS}=10V$.

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Revision History

Version	Date	Change
A	2022.1.10	
B	2022.5.7	1.Add note 1
C	2022.9.20	1.Add Reach,HF figure,2.Fig1~12 modify 3.Add It is suitable for
D	2025.2.25	Modify RDSON,ID.
E	2025.10.21	Correct package outline dimension and add reference land pattern